

Discription

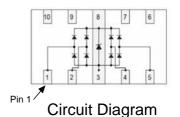
The HAZ1013-04F is a 4-channel ultra low capacitance rail clam ESD protection diodes array. Each channel consists of a pair of diodes that steer positive or negative ESD current to either the positive or negative rail . A zener diode is integrated in to the array between the positive and negative supply rails. In the typical applications,the negative rail pin (assigned as GND) is connected with system ground. The Positive ESD current is steered to the ground through an ESD diode and Zener diode and the positive ESD voltage is clamped to the zener voltage.



DFN2510-10L

Features

- ★ 4 channels of ESD protection;
- ★ Provides ESD protection to IEC61000-4-2 level 4
 - ±15kV air discharge
 - ±10kV contact discharge;
- ★ Channel I/O to GND capacitance: 0.4pF (Max)
- ★ Channel I/O to I/O capacitance: 0.6pF (Max)
- **★** Low clamping voltage;
- ★ Low operating voltage;
- ★ Improved zener structure;
- ★ Optimized package for easy high speed data lines PCB layout
- ★ RoHS compliant and Halogen Free.



Orderingin formation

Product ID	Pack	Qty(PCS)
HAZ1013-04F	DFN2510-10L	3000

Absolute Ratings(Tamb = 25°C)

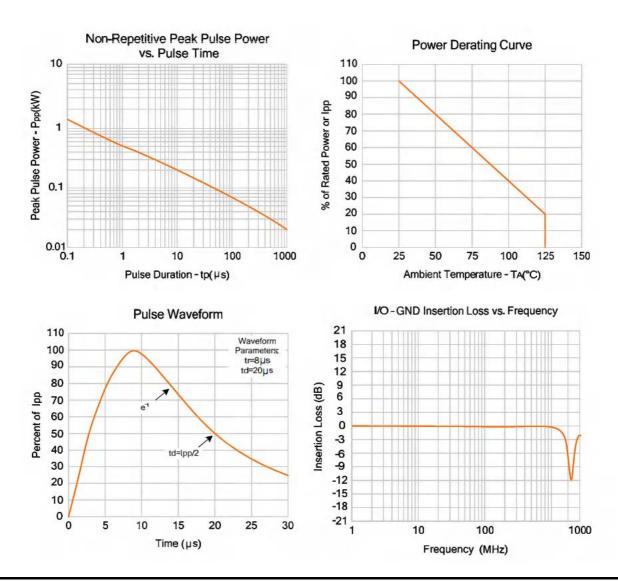
Symbol	Parameter		Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20μs)		70	W
I _{PP}	Peak Pulse Current(8/20us)		4	Α
TL	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _{op}	Operating Temperature Range		-40 to +125	°C
T _j	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD)	air discharge	±15	KV
		contact discharge	±10	IXV

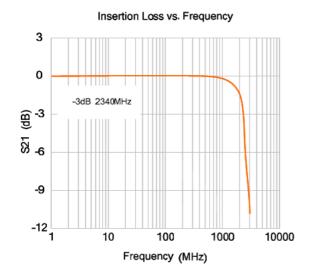


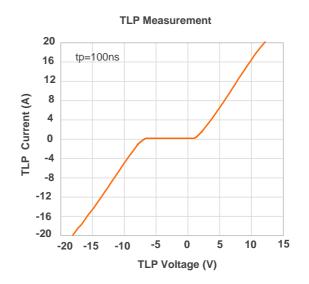
Electrical Characteristics (Ta= 25℃)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Reverse Working Voltage	VRWM	_	_	3.3	V	Any I/O pin to GND
Reverse Breakdown Voltage	VBR	5.6	-	_	V	It =1mA; Any I/O pin to GND
Reverse Leakage Current	lR	_	_	1	μA	VRWM =3.3V, T=25°C; Any I/O pin to GND
Positive Clamping Voltage	VC1	_	8	20	>	IPP=4A, tP=8/20µs; Positive pulse; Any I/O pin to GND
Negative Clamping Voltage	VC2	_	1.8	-	V	IPP=1A, tP=8/20µs; Negative pulse; Any I/O pin to GND
Junction Capacitance Between Channel	CJ1	_	0.3	0.4	pF	VR=0V, f=1MHz; Between I/O pins
Junction Capacitance Between I/O And GND	CJ2	_	0.6	0.8	pF	VR=0V, f=1MHz; Any I/O pin to GND

Typical Characteristics

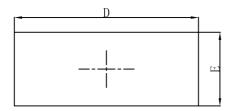


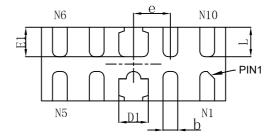




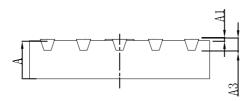


Outline And Dimensions





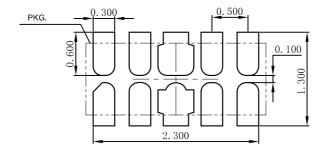
Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.450	0.550	0.017	0.022	
A1	0.000	0.050	0.000	0.002	
A3	0.152REF.		0.006REF.		
D	2.450	2.550	0.096	0.100	
Е	0.950	1.050	0.037	0.041	
D1	0.350	0.450	0.014	0.018	
E1	0.350	0.450	0.014	0.018	
b	0.150	0.250	0.006	0.010	
е	0.500TYP.		0.020TYP.		
L					

Soledering Footprint





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